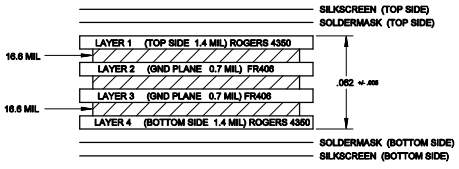
FSCM	DWG NO.	SH	REV

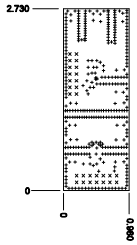
REVISIONS

ZONE	REV	DESCRIPTION	DATE	APPROVED

LAYUP DETAIL
4 LAYER



32 MIL WIDE TRACE AND 15 MIL AIRGAP FOR 50 OHM TRACES



Peregrine Semiconductor

LAYER 1 (PRIMARY SIDE)	3

17. THIS PCB FABRICATION MUST BE ROHS COMPLIANT IN MATERIAL AND MANUFACTURING PROCESSESS.
16. GROUND PLANE UNDER TRANSMISION LINES SHALL BE CONTINUOUS. PLEASE MAKE SURE THE PLANE IS NOT BROKEN UNDER TRANSMISSION LINES BY UL LOGOS.
15. ALL TRANSMISION LINES WITH 32 MIL WIDTH AND 15 MIL GAPS SHALL HAVE A TOLERANCE OF (+/- 1/2 MIL) ON THE TRACE AND GAP OF ARTWORK ORIGINALS. FAB VENDOR TO MODIFY RF TRACE WIDTH AND AIR GAP TO ACHIEVE 50 OHM +/- 5%
14. PLATE WITH 8 +/- 2 uIN MINIMUM IMMERSION GOLD OVER 175 +/- 75 uIN MINIMUM ELECTROLESS NICKEL OVER COPPER.
13. ALL BOARDS TO BE ELECTRICALY TESTED WITH SUPPLIED IPC-D-356A NETLIST (*.IPC FILE).
12. SURFACE MOUNT PAD SOLDER PLATING MUST BE FLAT TO A MAXIMUM OF .003" ABOVE BOARD SURFACE.
11. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
10. FABRICATE IN ACCORDANCE WITH IPC-6012, TYPE 3, CLASS 2.
9. BOARD SHALL MEET THE REQUIREMENTS OF UL796 WITH A FLAMMABILITY RATING OF 94V-O. VENDOR'S UL LOGO OR DESIGNATION AND DATE SHALL BE LOCATED ON THE BOTTOM SIDE.
8. REMOVE ALL BURRS AND BREAK SHARP EDGES .016" MAX.
7. APPLY SILKSCREEN, AS REQUIRED, USING WHITE EPOXY INK.
6. WARP OR TWIST OF BOARD SHALL NOT EXCEED 10%.
5. APPLY SOLDERMASK (LIQUID PHOTO IMAGEABLE) OVER BARE GOLD, SOLDERMASK TO BE PER IPC-SM-840, CLASS T, COLOR: GREEN. ALL EXPOSED CONDUCTIVE SURFACES TO BE GOLD COATED. CAUTION: SOLDERMASK DEFINED PADS ARE 0.002" DIAMETER LARGER THAN SMT PADS.
4. CONDUCTOR WIDTHS AND SPACING SHALL BE WITHIN +/-10% OF ARTWORK ORIGINALS UNLESS TIGHTER TOLERANCES ARE SPECIFIED.
3. ALL HOLES SHALL BE LOCATED WITHIN .003" DIAMETER OF TRUE POSITION. LAYER TO LAYER REGISTRATION SHALL BE WITHIN .003". ALL HOLES SURROUNDED BY LAND SHALL HAVE A MINIMUM ANNULAR RING OF .003".
2. UNLESS OTHERWISE SPECIFIED ALL HOLE DIMENSIONS APPLY AFTER PLATING. ALL PLATED THROUGH HOLES TO HAVE A MINIMUM OF .001" COPPER. VIA HOLES WITH 0.006" ARE DRILL SIZE.
1. MATERIAL: ROGERS 4350 TOP LAYER AND BOTTOM LAYER AND FR-408 INNER LAYERS. COPPER CLAD PLASTIC SHEET PER IPC-4101 TYPE GFN OVERALL BOARD THICKNESS TO BE .062 +/- .007.

NOTES: UNLESS OTHERWISE SPECIFIED

SIZE	QTY	SYM	PLATED	TOL
0.008	340	+	YES	+/-0.003
0.037	28	X	YES	+/-0.003

QTY REQD	FSCM NO.	PART OR IDENTIFYING NO.	NOMENCLATURE OR DESCRIPTION	MATERIAL SPECIFICATION

UNLESS OTHERWISE SPECIFIED ALL DIMENSIONS ARE IN INCHES TOLERANCES ARE:
FRACTIONS ± DECIMALS .XX ±.01 .XXX± ANGLES ±

MATERIAL

FINISH

DO NOT SCALE DRAWING

CONTRACT NO.

APPROVALS	DATE
DRAWN S. Johnson	1-16-12
CHECKED Tero Ranta	1-16-12
ISSUED	

NEXT ASSY	USED ON

APPLICATION

COMPANY Peregrine Semiconductor 9380 Carroll Park Drive San Diego, CA, 92121 (858)731-9400 Phone (858)731-9499 Fax

TITLE

DTC EVALUATION PCB

SIZE	FSCM NO.	DWG NO.	REV.
C		101-0660	01

SCALE: NONE SHEET 1 OF 1